

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name, and I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: ENHANCED CHIP SCALE PACKAGE FOR FLIP CHIPS, the specification of which (check applicable box(es):

which a patent is sought on the invent	ion entitled: ENHANCED CHIF	SCALE PACKAGE FOR FLIP CHII	<b>O</b> , alo
specification of which (check applicable	le bux(es).		
[X] is attached hereto;	as U.S. Ap	plication Serial No	and (if
[ X ]is attached hereto;  [ ]was filed on  [ ] was filed as PCT international applical applicable to U.S. or PCT application) was		<del></del> -	
I hereby state that I have reviewed a	and understand the contents o dment referred to above.	f the above-identified specification, Ir	
I acknowledge the duty to disclose accordance with 37 C.F.R. 1.56(a). foreign application(s) for patent or in application for patent or inventor's ce claimed or, if no priority is claimed be	ventor's certificate listed below	v and have also identified below any fore that of the application on which p	r foreign
Prior Foreign Application(s): Application Number		Day/Month/Year Filed	
disclose material information as deli applications and the national or PCT	vided by the first paragraph of the claim vided by the first paragraph of the claim and in 37 C.F.R. 1.56(a) which	of 35 U.S.C. 112, I acknowledge the noccurred between the filing date of application:	duty to the prior
. (p. p. 10-2-101-11-11-11-11-11-11-11-11-11-11-11-11	lonth/Year Filed	Status: patented, pending, abandone	
information and belief are believed that willful false statements and the latter 18 of the United States Code application or any patent issued there	to be true, and further that the like so made are punishable by e and that such willful false s reon.	ge are true and that all statements see statements were made with the krotner or imprisonment, or both, under tatements may jeopardize the validities.	§1001 of ity of the
	ne United States Patent and the and to transact all business in	Bennett, P.L.L.C., as identified by C radernark Office and as updated from the Patent and Trademark Office of 5).	
·	24112 PATENT TRADEMARK OFFICE	13/5/01	
1) Inventor's Signature	algela	Date Singa	nore
Inventor's Name(typed) <u>Yong Ké</u> First	Middle Initial	Family Name Citiz	enship
Residence (City) Singapore		Country) Singapore	
Post Office Address Blk 681, Cho	oa Chu Kang Crescent #10-552, S	i <u>ngapo</u> re 680681	

18/12 '01 16:16 FAX

*	•				a. Oak al			
2)	Inventor's Signature	P.D. Nath		_ Date	20 Sep 01			
•	Inventor's Name(typed)	Demonutation			Pinjala	India		
	Inventors Mame(typeo)	First	Middle Initial		Family Name	Citizenship		
	Residence (City) S	Singapore	(State/Foreign Country) Singapore					
	Post Office Address	st Office AddressBik 510, West Coast Drive, #06-315, Singapore_120510						
		Mala	lu k	Date	21 Sept-01	٠		
3)	Inventor's Signature	1 0000	Mar de	_ Dale	IYER			
	Inventor's Name(typed)	MAHADEVAN	K	<u> </u>	Mahadovan	India		
	litetion a Hamelihoa	First	Middle Initial		Family Name	Citizenship		
	Residence (City)	Singapore	(State/Foreign	Country)_	Singapore			
	Deat Office Address	Blv 723 #24-180 Cle	ementi West Street 2. S	Singapore 1	120723			

ALLEN & GLEDHILL 2003